

Jake enjoys working on a variety of intellectual property matters including patent litigation and trademark litigation.

Although a mechanical engineer, Jake has a passion for medical technologies. His first foray into the field was through undergraduate research in virtual laparoscopic surgery simulators. This ultimately led Jake to become a New Product Development Engineer at W.L. Gore and Associates, where he worked on endovascular devices prior to attending law school. At Gore, Jake developed valuable insight into innovation within a regulated industry. Working on small teams allowed Jake to gain experience ranging from planning and executing in-vivo studies to developing manufacturing processes. Among his accomplishments, Jake supported successful 510k and international regulatory submissions, drafted a design history file, and was a named inventor on one patent pending. After five formative years developing medical devices, Jake now offers broad industry experience in helping clients protect their IP assets.

Jake attended Chicago-Kent College of Law as an Honors Scholar and graduated magna cum laude. While at Chicago-Kent, Jake served as an Executive Articles Editor of the Law Review, served as the Vice President of the Intellectual Property Law Society, and was inducted into the Order of the Coif.

Education

Rensselaer Polytechnic Institute 2014, B.S., Mechanical Engineering

Chicago - Kent College of Law 2022, J.D.

Admissions

Bar Admissions 2022, Illinois

Court Admissions U.S. District Court for the Northern District of Illinois U.S. Patent and Trademark Office

Practices

Litigation PTAB Litigation

https://bannerwitcoff.com

Industries

Mechanical Engineering

Recent News + Events + Related Publications

NEWS - 01.22.24 PTAB Highlights | Takeaways from Recent Decisions in Post-Issuance Proceedings

Featured, Non-news/events/press, general content etc. - 10.31.22 Banner Witcoff Adds Four New Associates in Chicago and DC Offices

NEWS - 10.24.22

PTAB Highlights | Takeaways from Recent Decisions in Post-Issuance Proceedings